

#### ABSTRACT OF THE DISCLOSURE

An object of the present invention is to reduce the number of steps necessary for connecting between a wiring circuit board and a printed circuit board and to achieve a low-cost wiring circuit board. A wiring circuit board (2) includes an insulating film (4), a bump (6), an etching barrier layer (8), and a wiring layer (10). The bump (6) is made of copper and formed to penetrate through the insulating film (4). A top face of the bump (6) is exposed at a surface of the insulating film (4) flush therewith. The etching barrier layer (8) is made of nickel (Ni) and formed underneath the bump (6). The bump (6) is connected to the wiring layer (10) through the etching barrier layer (8). A solder ball (12) is formed on the top face of the bump (6). A printed circuit board (14) as a rigid board is connected to the wiring circuit board (2). A wiring layer (16) is connected to the bump (6) through the solder ball (12) to thereby mount the wiring circuit board (2) to the printed circuit board (14).